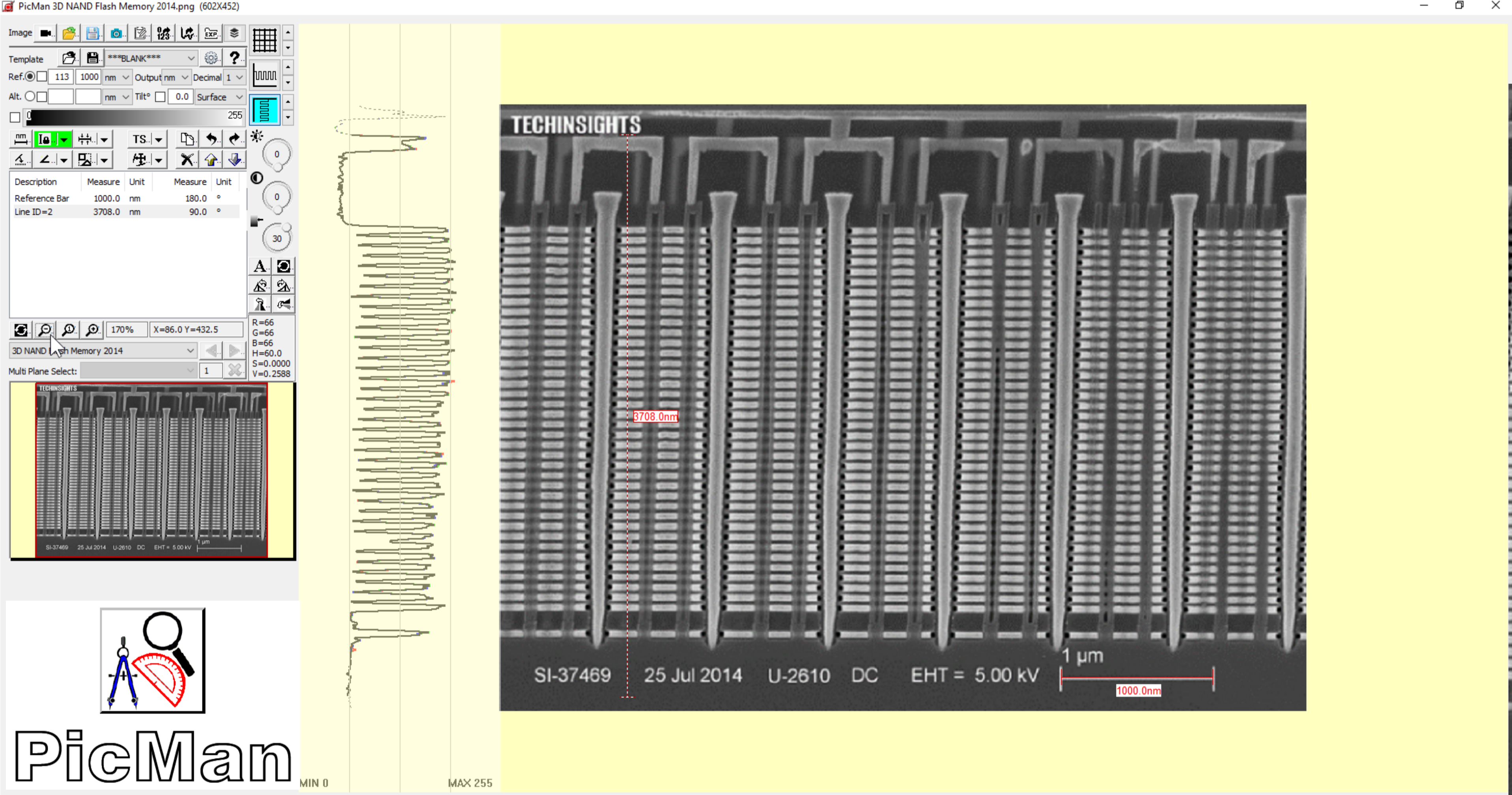


Image-based Dimensional Analysis for Semiconductor and MEMS Structures

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A newly developed user friendly, unified image processing software (PicMan from WaferMasters, Inc.) is introduced, along with a few digital image examples in of 3D VNAND flash memory devices and photomasks process monitoring and qualifications. Suggestions of the effective use of digital images in terms of quantitative and statistical analysis will be introduced using sample images. The image processing software enables end users to analyze digital images of any format, on their own PCs, very easily and accurately. Improved digital image analysis by end users will greatly enhance the understanding of characterization results and shorten development cycles. Many different levels of automation of image-based measurements and quality control are possible by customization.



Dimensional Analysis

